

## REMARKS

Applicants appreciate the thoroughness with which the Examiner has examined the above-identified application. Reconsideration is requested in view of the amendments above and the remarks below.

### **Rejection under 35 U.S.C. § 102**

Claim 18 stands rejected under 35 U.S.C. § 102 as being anticipated by Edelstein, et al. (U.S. Patent Application Publication No. 2005/0121768 A1). Applicants respectfully traverse this rejection.

Attached hereto and made a part hereof is a declaration under 37 C.F.R. § 1.131 removing the Edelstein, et al., patent application publication as a reference. The claimed invention was conceived and reduced to practice in the U.S. prior to December 5, 2003, the effective filing date of the Edelstein application. The conception and reduction to practice in the U.S. is shown by the appended copy of an invention disclosure form filled out by one of the inventors, Jon A. Casey, Ph.D., describing the invention disclosed in the subject patent application. The appended invention disclosure discloses the use of a method for metallizing either blind or through vias in silicon. It teaches forming a low coefficient of thermal expansion composite or suspension, relative to pure metals such as copper, and filling the via holes in the silicon with the newly developed paste. It discloses the controlled sintering of copper and a CTE matched insulator. The disclosure further teaches having the paste contain a high solids loading in suspension. The sintering temperature is taught to be high

enough to allow the metal particles to sinter together, and low enough so that the CTE particles remain unsintered.

Since this disclosure predates the filing date of the U.S. patent application publication of Edelstein, et al., applicants respectfully submit that Edelstein be removed as a reference.

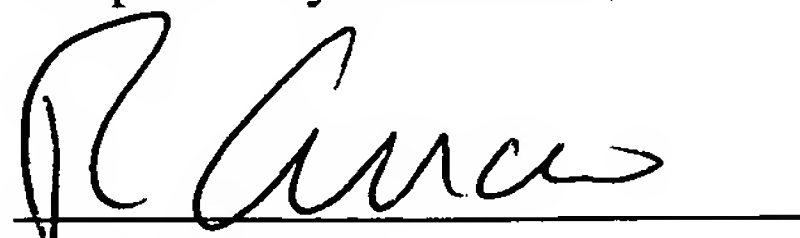
**Rejection under 35 U.S.C. § 103**

Claims 1-17 and 19-30 stand rejected under 35 U.S.C. § 103 as being obvious from Edelstein, in view of Aoude, et al. (U.S. Patent No. 5,337,475. Applicants respectfully traverse this rejection.

Applicants submit that with the removal of the Edelstein patent publication, claims 1-17 and 19-30 remain in a condition for allowance.

It is respectfully submitted that allowance of the entire case is proper. Reconsideration and issuance of a notice of allowance are respectfully solicited.

Respectfully submitted,




Robert Curcio  
Reg. No. 44,638

**DeLIO & PETERSON, LLC**  
121 Whitney Avenue  
New Haven, CT 06510-1241  
(203) 787-0595

**CERTIFICATE OF MAILING**

I hereby certify that this correspondence is being deposited with the United States Postal Service on the date indicated below as first class mail in an envelope addressed to Mail Stop \_\_\_\_\_, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

Name: Barbara Browne Date: October 26, 2005 Signature:   
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